

**Amendments to the Specification**

Please replace paragraph [0001], on page 1, with the following rewritten paragraph:

-- This application claims priority from U.S. Provisional Application number 60/188,570, titled "Flip Chip Interconnection Structure". This application is related to commonly assigned copending U.S. Application ~~Atty. Docket No. 60084-300201~~ No. 09/802,375 titled "Packaging Structure and Method" filed March 9, 2001 and U.S. Application ~~Atty. Docket No. 60084-300101~~ No. 09/802,443 titled "Flip Chip-in-Leadframe Package and ~~Method~~ Process" filed March 9, 2001; both said related applications ~~are being filed on the same date as this application,~~ and are hereby incorporated by reference in their entireties herein. --